

ABSTRACT OF THE DISCLOSURE

In a method of manufacturing a camera module having a CMOS image sensor, a semiconductor chip to serve as a light sensor is mounted on an optical-component-mounting face of a wiring substrate mother board and, after bonding wires are connected to the semiconductor chip, a lens barrel is joined to the wiring substrate mother board so as to cover the semiconductor chip. A position adjustment pin and a through hole are provided on the lens barrel and the wiring substrate mother board respectively outside a junction face between the lens barrel and the wiring substrate mother board to be used for adjusting the position of the lens barrel with respect to the wiring substrate mother board by inserting the position adjustment pin into the through hole.